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12-Switch Matrix Manager for Automotive Lighting

MAX20092

General Description

The MAX20092 12-switch matrix manager IC for automotive lighting applications includes a 12-switch array for bypassing individual LEDs in a single- or dual-string application. It features 12 individually controlled n-channel MOSFET switches rated for 10V with on-resistance of 0.100Ω. A single current source can be used to power all the LEDs connected in series. Individual LEDs can be dimmed by turning on and off the bypass switches across each LED, and can also be configured in 2 strings with 6 switches in series per string and 4 strings with 3 switches per string. A separate current source powers each string. Each switch can be connected across 1 or 2 LEDs in series. The IC also includes an internal charge pump that provides power for the gate drive of each of the LED bypass switches. The low on-resistance of the switches minimizes conduction loss and power dissipation.

The IC features a serial peripheral interface (SPI) for serial communication. The MAX20092 is a slave device that uses the SPI to communicate with an external microcontroller (μC), which is the master device. Each of the 12 switches can be independently programmed to bypass the LEDs across each of the switches in the string. Each switch can be turned fully on, fully off, or dimmed with or without fade-transition mode. The PWM frequency can be set by an internal oscillator or set to an external clock source. The IC features open-LED protection as well as open- and short-LED fault reporting through the SPI. The MAX20092 is available in a 32-pin (5mm x 5mm) sidewettable TQFN (SWTQFN) package with a thermally enhanced exposed pad.

Applications

- Automotive Front-Light Systems
- Automotive Tail-Light Systems
- Automotive Matrix-Lighting Systems

Benefits and Features

- Automotive Ready: AEC-Q100 Qualified
- Flexible Configuration Allows the Use of the Same Device in Different Applications
	- Single-, Dual-, and Quad-String Configurations
	- Up to 12 Switches in Series in Single-String **Configurations**
	- Up to 6 Switches in Series in Dual-String **Configurations**
	- Up to 3 Switches in Series in Quad-String **Configurations**
	- Up to 2 LEDs per Switch
- Optimal PWM Dimming Arrangement Provides Excellent Dimming Performance
	- Programmable 12-Bit PWM Dimming
	- Fade Transition Between PWM Dimming States
	- Internal Clock Generator or External Clock for PWM Dimming
- Protection Features and Package Improve Reliability
	- Open-LED Protection
	- Programmable Open-LED and Shorted-LED **Threshold**
	- Open- and Shorted-LED Fault Reporting
	- Thermally Enhanced 32-Pin SWTQFN Package

[Ordering Information](#page-61-0) appears at end of data sheet.

Simplified Block Diagram

^{19-100310;} Rev 1; 11/19

Absolute Maximum Ratings

Continuous Power Dissipation (Single-Layer Board) $(T_A = +70^{\circ}C,$ derate 21.3mW/°C above +70°C).....1702.1mW Continuous Power Dissipation (Multilayer Board) $(T_A = +70^{\circ}C,$ derate 33.2mW°C above +70°C).........2658mW

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these
or any other conditions beyond those in *device reliability.*

Package Information

32-Pin (5mm x 5mm) SWTQFN

For the latest package outline information and land patterns (footprints), go to **www.maximintegrated.com/packages**. Note that a "+", "#", or "-" in the package code indicates RoHS status only. Package drawings may show a different suffix character, but the drawing pertains to the package regardless of RoHS status.

Package thermal resistances were obtained using the method described in JEDEC specification JESD51-7, using a four-layer board. For detailed information on package thermal considerations, refer to **www.maximintegrated.com/thermal-tutorial**.

Electrical Characteristics

(Input voltage and enable = V_{IN} = V_{EN} = V_{DDIO} = 5V, T_A = T_J = -40°C to +125°C, unless otherwise noted. Typical values are at T_A = +25°C.) (Note 1)

Electrical Characteristics (continued)

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Electrical Characteristics (continued)

(Input voltage and enable = V_{IN} = V_{EN} = V_{DDIO} = 5V, T_A = T_J = -40°C to +125°C, unless otherwise noted. Typical values are at T_A = +25°C.) (Note 1)

Note 1: Limits are 100% tested at T_A = +25°C. Limits over the operating temperature range and relevant supply voltage range are guaranteed by design and characterization.

Note 2: Excludes bond-wire resistance. Typical package bond-wire impedance = 15mΩ per pin.

Note 3: Static logic inputs with V_{IL} = GND and V_{IH} = V_{DDIO} (Note 1). SCSB = V_{IH} (if pullup active).

Note 4: No internal safety pullup/pulldown impedances active, input buffers only.

Note 5: Internal safety pullup/pulldown impedances available, with enable function.

Note 6: Applications must afford time for the device to drive data on the SDO bus and meet the µC setup time prior to the µC latching in the result on the following SCLK RE. In practice, this is determined by loading and µC characteristics, and the relevant t_{DOT}/t_{DOE}.

Pin Configuration

Pin Description

Pin Description (continued)

Functional Diagram

Detailed Description

The MAX20092 12-switch matrix manager IC for automotive lighting includes a 12-switch array for bypassing individual LEDs in a single- or dual-string application. The IC features 12 individually controlled n-channel MOSFET switches rated for 10V with an on-resistance of 0.100Ω. A single current source can be used to power all the LEDs connected in series. Individual LEDs can be dimmed by turning on and off the bypass switches across each LED. The IC can also be configured in two strings with 6 switches in series per string or 4 strings with 3 switches per string. A separate current source powers each string. Each switch can be connected across one or two LEDs in series. The IC also includes an internal charge pump that provides the gate drive for each of the LED bypass switches. The low on-resistance of the switches minimizes conduction loss and power dissipation.

The IC features a serial peripheral interface (SPI) for serial communication. The IC is a slave device and uses the SPI to communicate with an external microcontroller which is the master. Each of the 12 switches can be independently programmed to bypass the LEDs across each of the switches in the string. Each switch can be turned fully on, fully off, or dimmed with or without a fade transition mode. The PWM frequency can be set by an internal oscillator or can also be set to an external clock source. The IC features open-LED protection, as well as open- and short-LED fault reporting through SPI. The IC is available in a 5mm x 5mm 32-pin side-wettable TQFN (SWTQFN) package with a thermally enhanced exposed pad. The SPI is capable of operating from 1.8V to 5.5V and is driven from the V_{DDIO} supply.

Each switch has an individual driver, overvoltage-protection circuit, and a diagnostic circuit referenced to the source of that switch. This configuration allows for fully dynamic operation with the switches above it and below it. The IC monitors overvoltage conditions on each switch and automatically protects them in the event of an open-LED connection. The open-LED fault can be programmed at one of the two threshold levels: 4.5V or 9.0V. The short-LED fault can also be programmed at one of two threshold levels: 1.0V or 4.4V. When a shorted-LED fault is detected in a channel, the channel switch continues with what it is doing. The IC detects open-LED conditions as well as shorted-LED conditions and reports them through the fault-reporting network. The IC also detects and reports a thermal-warning condition. The FAULTB signal pulls low if thermal shutdown is activated.

Power-On Reset

Once the IC is powered, an internal power-on reset (POR) signal sets all the registers to their default states. All 12 switches are in the on state upon a POR (all LEDs are off). The LEDs remain off until a command is received by the SPI. To ensure reliable operation, the IN supply voltage (V_{IN}) must be greater than V_{IN-POR} . If V_{IN} falls below V_{IN-POR}, the registers reset to their default state. The IN voltage must be greater than V_{IN-POR} and $EN =$ 1 for SPI operation.

Enable Function (EN)

When the EN pin is low, all registers are reset to their default values and all the bypass switches are turned on.

When the EN pin is brought high, the IC is enabled and the SPI registers can be written to, as described in the *[SPI Transactions](#page-17-0)* section. The bypass switches remain in their default on state until the SPI is used to enable LED dimming.

Internal Switches

Each switch connected between DRAINn and DRAINn-1 has a typical on-resistance of 0.10Ω. This measurement includes the on-resistance of the internal switch and the resistance of the bond wires to the DRAINn and DRAINn-1 pads. Each bypass switch, when driven to an off state, allows the string current to flow through the corresponding parallel-connected LED, turning the LEDs on. Driving the bypass switch to an on state shunts the current through the bypass switch and turns the LEDs off. Each bypass switch can have one or two LEDs in series across it.

LED Fault Detection and Protection

The IC is able to detect a shorted LED, open LED, and open trace between the device and the LED. To detect and report an LED fault, several conditions must be met. First, the LED switch must be operating, so SW_GO_EN and the EN pin should both be high. LED-open and LEDshort detection requires the switch be open, so the duty cycle must be greater than zero. Conversely, open-fault detection requires the switch to be closed, so PWM duty cycle must be less than 100%. In general, it takes up to one dimming cycle to make sure these conditions have been met after a fault condition is applied. This period depends on the PWM dimming frequency.

LED Open-Fault Detection and Protection

An open-LED fault is triggered when the voltage between the individual LED switch DRAIN node and switch SOURCE node exceeds V_{OTH} and is reported in register STAT_OPEN_LED (0x06). The switch is closed when an open-LED detection occurs and remains closed until the next PWM dimming open-switch request occurs. By default, the open fault results in the FAULTB pin being driven low; however, open faults can be masked by writing 0b1 to the MSK OPEN LED bit in the CNFG MSK (0x04) register. If an open-LED fault is detected multiple times, it is recommended that the OPEN_OVRD (0x08) register be updated to force the corresponding LED switch to remain closed continuously to provide a bypass for the faulty LED.

LED Short Detection

A short-LED fault is triggered when the voltage between the switch DRAIN node and the switch SOURCE node is below V_{STH} for an open switch condition, and is reported in the STAT_SHRT (0x09) register. The LED short comparator is sampled at the end of each LED pulse to avoid false detects during the beginning of the pulse. No action is taken with the switch in response to detecting a short-LED fault, with it continuing to operate as programmed. The short fault, by default, results in FAULTB being driven low; however, short faults can be masked by writing 0b1 to MSK_SHRT in the CFG_MSK (0x04) register.

Open-Trace Detection

An open-trace fault is triggered when the current through the closed switch is less than I_{I}_{F} MIN and is reported in the STAT_OPEN_TRACE (0x07) register. No action is taken with the channel switch in response to detecting an open trace, with it continuing to operate as programmed. By default, the open-trace fault results in the FAULTB pin being driven low; however, open-trace faults can be masked by writing 0b1 to MSK_OPEN_TRACE in the CFG_MSK (0x04) register.

The open-trace fault is sampled before the rising PWM edge, which is the edge turning the switch off. If there is an open trace to the drain side of the switch, the switch above it has to be open during the PWM rising edge of the switch that is detecting the condition. For example, if there is an open trace on the drain side of N1 (see [Figure 1](#page-10-0)), then N2 has to be open when N1 is turning on and similarly, for detecting an open-trace condition on the drain of N0 (N1 must be open when N0 is turning on). For the top-most-switch N2 drain connection, and the bottommost-switch source connection, there is no constraint to detect the open-trace condition.

Thermal Shutdown

The IC features an on-chip temperature-protection circuit to prevent the device from overheating.

When the die temperature rises above the thermalwarning threshold (+150ºC), the TH_WARN bit is set, causing the FAULTB pin to be asserted if unmasked, but no action is taken with the switches. If asserted, the FAULTB pin remains asserted until the die temperature drops below the thermal-warning threshold, and a read of the STAT_GEN (0x05) register has occurred. To clear the TH_WARN bit, the die temperature must be below the thermal-warning threshold.

When the die temperature rises above the thermalshutdown threshold (+160ºC), the TH_SHDN bit is set, causing the FAULTB pin to be asserted and all switches to either be closed (LEDs turned off) or opened (LEDs turned on), depending on the value of the CNFG_MSK (0x04) register. Switches remain static and the FAULTB pin remains asserted until the die temperature drops below the thermal-warning threshold, and a read of the STAT_GEN register has occurred.

When the device recovers from thermal shutdown, it resumes operation from where it was before the thermal shutdown. The TH_WARN and TH_SHDN bits are cleared on read.

Figure 1. Open-Trace Detection

FAULTB Pin Operation

The FAULTB pin is an active-low, open-drain output. The IC asserts a fault if any of the bits are set in the SPI STAT_GEN register (0x05). See the STAT_GEN register (0x05) in the *[Register Map](#page-26-0)* section and the subsequent register table for more details on the definition of each bit. Once all the bits have been cleared by reading the appropriate SPI registers, the FAULTB pin is released. **Note:** If the conditions causing the fault bit(s) to be asserted persist, the bits are immediately set again. The FAULTB pin remains low.

PWM Clock and Synchronous Operation with Multiple Devices

The PWM clock for the IC can be selected from the internal oscillator or from an external clock source driving the CLK pin. The CLK pin is bidirectional, allowing a single device to be the master clock, providing a common clock source to multiple devices. The PWM clock source and CLK pin direction are configured through PWM_CLK[1:0] in the CNFG GEN (0x03) register. The default value is internal oscillator with the CLK pin disabled. For synchronous operation with multiple devices, use the PWM_CLK_SEL bits in the CNFG_GEN (0x03) register to set the master with internal oscillator and CLK pin output, and the slave devices with external oscillator and CLK pin input.PWM dimming frequency is programmable by setting the value of the DIV[1:0] bits in the CNFG_GEN (0x03) register, which sets the divide ratio for both the internal (8.192MHz) and external clock sources. When disabled, the CLK pin is high impedance with a 100kΩ pulldown resistor.

Parallel Operation for Higher Current Applications

The switches in the IC can handle current up 1.6A (max); however, for applications that require higher currents, the switches can be configured in parallel. For example, if the current capability needs to be doubled with 6 LEDs, connect switch SW0 in parallel to SW6, SW1 in parallel to SW7, and so on. Make sure the switches connected in parallel have the same phase shift and PWM dimming duty cycles.

PWM Dimming

The IC provides 12-bit programmable dimming on each individual switch. An internal 12-bit counter (COUNT) is generated according to the clock settings. The switch turns off when COUNT is equal to the delay set by the corresponding PSFT register and stays off until the COUNT exceeds the sum of PSFT and PWM duty-control registers. In this way, the duty cycle and relative phase shift of the individual switches can be set independently (see [Figure 2](#page-11-0)).

Figure 2. PWM Dimming

Dimming With and Without Fade

Each switch of the IC can be independently programmed to perform dimming without fade transition, or dimming with fade transition. For dimming without fade transition, the dimming changes from the initial value to the target value in one dimming cycle. For dimming with fade transition, the dimming changes transitionally step by step, starting from the initial value to the target value in multiple dimming cycles, following a predetermined exponential curve.

To enable dimming with fade transition, set the FADE bit to 1 and the DUTY bits to the target value for the specific switches. Each transitional step value is calculated using 12 bits according to the following formula:

DUTYnext = DUTYnow x CF

where DUTY is the duty cycle, and CF the constant factor.

 $CF = 1.0625$ and $CF = 0.9375$ for an up transition and down transition, respectively.

DUTYnext continues to be updated according to the formula until DUTYnext reaches the target value. The transition period is defined by the TDIM_ register for the switch. The number

Table 1. RGRADE Recommended Values

of transitional steps depends on the distance between the initial value and the target value. The maximum number of transitional steps from 1(/4095) to 4095(/4095) is 115 steps. See [Figure 3](#page-12-0) for the up-transition curve. The number of transitional steps depends on the distance between the initial value and the target value. The maximum number of transitional steps from 4095(/4095) to 1(/4095) is 111 steps. See [Figure 4](#page-12-1) for the down-transition curve.

Duty-cycle steps smaller than CF update in 1 step.

Each step runs TDIM_ PWM dimming cycles, and each dimming cycle consists of 4096 clock cycles; therefore Tstep = TDIM \times 4096.

Grade Selection

The IC provides eight levels of detection between 0 and 4V on the RGRADE pin, which can be read back as part of the REV_ID in the NO_OP (0x00) register. The RGRADE pin sources 50μA, allowing the use of an external resistor between RGRADE and GND to set the voltage level. See [Table 1](#page-12-2) for threshold levels and recommended resistor values.

Figure 3. Up-Transition Curve Figure 4. Down-Transition Curve

4-Wire Serial Interface

General Description

The IC recognizes transactions during which SCSB is low. The serial peripheral interface (SPI) latches SDI input data on SCLK's rising edge and executes commands on SCSB's rising edge, subject to qualification criteria. SDO is active when SCSB is low, and is held in three-state when SCSB is high. Star connections of up to 26 devices are supported. Internal pullup and pulldown resistors are included on all input pins to enhance safety in the event of a broken wire/trace. SPI_ERR and CRC checks are offered for interface verification.

The following features are supported by the SPI:

- 32-Bit SPI Frame
- **SCSB Active-Low Device Selection**
- **SCSB Rising-Edge Transaction Execution**
- SDI Data Latched on SCLK Rising Edge
- 7-Bit Register Addressing with 13-Bit Data
- 128 Write/Read Accessible Registers (00-7F\h)
- **Embedded CRC3 Checking**
- SPI_ERR Interface Error-Indicator Bit
- Configurable Internal Pullup/Pulldown Terminations on All Input Pins
- Star Connections of Up to 26 Devices Supported on Single SCSB Line

Overview

The MAX20092 interface is SPI, QSPI, Microwire, and DSP compatible. The operation and timing criteria of the SPI is shown in [Figure 5](#page-13-0). The device is programmed by a 32-cycle SPI instruction, framed by a low interval on SCSB. The start of the transaction is defined by the SCLK rising edge following the SCSB falling edge (subject to t_{CSH0} and t_{CSS0} timing criteria). Transactions including a number of SCLK rising edges not equal to 32 are not qualified for execution (also based on t_{CSA} , t_{CSH1} , and t_{CSO} timing criteria). Qualified transactions are executed on the rising edge of SCSB. To abort a command sequence, the rise of SCSB must precede a qualified 32nd rising edge of SCLK (meeting the t_{CSA} timing requirement).If SCLK stops toggling for more that 256μs while SCSB remains low, the device declares a SPI timeout error and asserts CLK_ERR.

The SDI content of the SPI transaction consists of a leading read/writeB (R/WB) bit followed by device ID, address, input data information, and CRC. Data is latched into the registers on SCLK rising edges, subject to setup and hold criteria (t_{DS} , t_{DH}).

SDO is actively driven during intervals where SCSB is low. SDO is initially driven by the device when SCSB falls $(t_{DOF}$ timing applies), presenting the MSB of the output data (the SPI_ERR bit for all transactions). Following the initial SCLK rising edge, SDO is updated in response to SCLK falling edges, conforming to hold- and transitiontime criteria (t_{DOH,} t_{DOT}), allowing the μ C to latch the data on SCLK rising edges. When SCSB is high, the SDOUT line is high impedance, allowing other devices to access the SDO bus.

Figure 5. SPI Timing Diagram

Device Connections

The SPI ensures compatible operation with standard microcontrollers (µCs) from a variety of manufacturers. The µC always operates as the master, and is able to initiate read and write transactions to individual slave devices (using standard connections), or groups of slave devices in a star configuration. The device(s) always operate in the slave role when connected to a µC and cannot initiate a SPI transaction.

The SCLK line should be driven by the master and hooked up to all slave devices. Only the slave devices (or group of slave devices) with its SCSB line low will accept SCLK. SPI transactions to the slave devices are defined by SCLK rising edges. The MAX20092 can therefore support SPI formats with (CPOL=0, CPHA=0) or (CPOL=1, CPHA=1), see [Figure 6](#page-14-0) for alignment examples. The SDI line should be hooked up to a master-out/slave-in (MOSI) port. A single SDI line can be routed to all SPI slave devices sharing the interface, but only the slave device (or group of slave devices) with the SCSB line low will accept SDI data. The µC should update SDIN in response to SCLK falling edges so the slave can latch data in on SCLK rising edges. The SDO line should be hooked up to a master-in/slave-out (MISO) port. A single SDO line can be routed to all slave SPI devices sharing the interface, but only the slave device (or group of slave devices) with its SCSB line low can access and drive the shared SDO bus. The slave updates SDO in response to SCLK falling edges, so the µC can latch data in on SCLK rising edges.

Figure 6. SPI Transaction Format

Star Device Connections

The IC's SPI allows multiple devices to share the interface, with the active device for the transaction being selected by a predetermined device ID number. The SCSB, SCLK, SDI, and SDO lines are common to all devices. Transaction-qualification criteria remains in effect, and in write mode the device executes the instructions present in the 32 bits of a qualified transaction. In read mode, the device returns the requested data through SDO during the read-mode transaction.

An example of a standard Star connection is shown in [Figure 7.](#page-15-0)

Figure 7. Star Connections

Device Identification Number

Each device in the star connection is given a unique device ID number through hard-wiring pins ADDR2, ADDR1, and ADDR0. Each pin can be connected to three different values (V_{DD} , GND, and SDI), for a total of 26 valid combinations. The combination of {GND, GND, GND} is reserved for a general-call ID and should not be used.

Table 2. Device ID Mapping

Individual Call, Global Call, Cluster-Call Command For the first 8 bits of the transaction, the master sends: {Read/write bit, CMD1, CMD0, ID4, ID3, ID2, ID1, ID0} Where CMD[1:0] is the Call-Type command. This field allows the master to access:

- A single device (individual call)
- Multiple devices (cluster call), or
- All devices (global call) on the shared SCSB line

Safety Pulldown Resistors

To guard against broken SPI connections, the IC includes internal safety terminations on all interface input ports. SCLK and SDI have internal pulldowns to GND. SCSB and RESETB (if present) have internal pullups to V_{DDIO} . All safety resistors are 100kΩ nominal.

The internal safety resistors can be individually enabled or disabled using SPI configuration bits (SFT_CLK, SFT_ SDI, SFT_SCSB) with a high state indicating the safety termination is enabled/engaged and a low state indicating it is disengaged. This allows the user to eliminate loading currents when the safety resistors are not needed.

SPI Transactions

Write-Mode Transactions

A properly constructed write-mode transaction is made up of 32-bit data frames. Each SDI data frame from the master (or the previous device in the chain) contains a R/WB bit, a 2-bit individual call command, a 5-bit device identification number, a 7-bit address, 13 bits of input data or instructions, and a 3-bit CRC. During a write-mode transaction, the device outputs data on the SDO line; both transaction log and repeated transaction data are transferred through SDO. The device only accepts and executes qualified SPI transactions based on the last 32 bits of data received. Details of write-mode transactions are explained below and summarized in [Figure 8.](#page-17-1)

Write Bit - R/WB = 0 (DIN31):

Write-mode transactions are identified by R/WB = 0 in the MSB position of a 32-bit data frame.

Individual Call Command - CMD[1:0] = 01 (DIN[30:29]):

Individual write transactions are identified by CMD[1:0] = 01 in the DIN[30:29] positions of the frame.

Figure 8. Write-Mode Transaction

Table 3. Call Type Command

Device ID - ID[4:0] (DIN[28:24]):

Note: After the 8th bit has been received (rising 8th SCLK edge), the selected slave continues to drive the SDO line with the contents of the transaction log for the remaining 24 bits. The other slaves release the SDO line such that only one slave is driving.

Address - A[6:0] (DIN[22:16]):

Write-mode transactions allow new information to be written to internal configuration registers within the device. The configuration register address to be written is indicated by A[6:0] within the data frame. In this format, up to 128 register addresses are supported (0\h thru 7F\h) for write-mode access.

Note: DIN23 must always be 0.

Input Data - DIN[12:0] (DIN[15:3]):

The next 13 bits of data in the 32-bit data frame represent data that will be written to the requested register, or describe internal operations to be executed.

SDI CRC Bit - CRCi[2:0] (DIN[2:0]):

Write-mode transactions are protected by a 3-bit cyclic redundancy check (CRC) on the SDI data frame. CRC is provided by the master on the last 3 bits on SDI.

CRC is calculated by applying the DIN[31:3] message (i.e., Address + Input Data) on polynomial $0x5 (x^3 + x^1 +$ x0) with a start value of binary 000.

The receiving device (slave) will calculate its own CRC using the same polynomial and starting value. The slave only accepts/executes the command if its own CRC matches the last 3 bits on SDI.

Output Data - DO[31:0] and LOG[23:0]:

During write-mode transactions, the device outputs data through the SDO line.

In write mode, the device pulls down SDO immediately following the falling edge of SCSB. The first 8 bits are always 0. The remaining 24 bits are the contents of the internal transaction log register (LOG[23:0]).

See the *[Internal Transaction Log](#page-23-0)* section for a detailed explanation of content.

If further SCLK cycles are provided, SDO outputs 0 for the remainder of the transaction frame and CLK_ERR is set.

Note: This method also provides the µC an opportunity to check the SPI integrity, since the transaction log content of the previously qualified/executed transaction will be relayed back to the µC through SDO during each complete single or extended transaction.

Write-Mode Qualification Check (SPI_ERR):

To qualify for write-mode execution, the following conditions must be met:

- SPI transaction must be exactly 32 bits in length (no CLK_ERR recorded)
- SDI data frame CRC check must pass (no CRC_ERR recorded)
- A[6:0] must select a valid write-accessible register or command (no W_ERR recorded)

If the SPI transaction is qualified, the instruction is executed, any requested internal register contents are updated, and the Internal Transaction Log is updated to indicate the successful transaction.

If the SPI write transaction is not qualified, the instruction is not executed, the device's internal SPI_ERR indicator and appropriate SPI diagnostic bit are set, and the Internal Transaction Log is updated to indicate the failed transaction. The SPI_ERR bit is returned in response to later read and write-mode transactions, notifying the µC that the SPI interface may be compromised.

Read-Mode Transactions:

A properly constructed read-mode transaction is made up of 32-bit data frames. Each SDI data frame from the master contains a R/WB bit, a 2-bit Individual Call command, a 5-bit Device Identification number, a 7-bit address, 13 bits of data set to all zeros (000\h), and a 3-bit CRC.

During a read-mode transaction, the IC outputs data on the SDO line; the content of the SDO data frame is described in detail below. The MAX20092 only accepts qualified SPI transactions, based on the last 16 bits of data received. Details of read-mode transactions are explained below and summarized in [Figure 9.](#page-19-0)

Read Bit - R/WB = 1 (DIN31):

Read-mode transactions are identified by R/WB = 1 in the MSB position of a 32-bit data frame.

Individual Call Command - CMD[1:0] = 01 (DIN[30:29]):

Individual write transactions are identified by CMD[1:0] = 01 in the DIN[30:29] positions of the frame.

Device ID - ID[4:0] (DIN[28:24]):

Note: After the 8th bit has been received (rising 8th SCLK edge), the selected slave continues to drive the SDO line with the contents of the transaction log for the remaining 24 bits. The other slaves release the SDO line such that only one slave is driving.

Address - A[6:0] (DIN[22:16]):

Read-mode transactions allow new information to be read from internal registers within the device. The register address to be read back is indicated by A[6:0] within the data frame. In this format, up to 128 register addresses are supported (00\h thru 7F\h) for read-mode access. **Note:** DIN23 must always be 0.

Input Data - DIN[12:0] (DIN[15:3]):

The 13-bit input data in a read mode must be set to zero (000\h).

SDI CRC Bit - CRCi[2:0] (DIN[2:0]):

Read-mode transactions are protected by a 3-bit cyclic redundancy check (CRC) on the SDI data frame. CRC is provided by the master on the last 3 bits on SDI.

CRC is calculated by applying the DIN[31:3] message (i.e., Address + Input Data) on polynomial $0x5 (x^3 + x^1 +$ x0) with a start value of binary 000.

The receiving device (slave) calculates its own CRC using the same polynomial and starting value. The slave only accepts/executes the command if its own CRC matches the last 3 bits on SDI.

Output Data - Current Status[6:0]+Data Requested[13:0]:

In a read operation, the device pulls down SDO immediately following the falling edge of SCSB. **Note:** The first 8 bits of the transaction are always 0.

The device then relays the SPI_ERR status, up to 7 bits of general-status data (STR[6:0]), the 13 bits of data requested by A[6:0], and a calculated 3-bit CRC in direct response to an incoming read-mode transaction.

If further SCLK cycles are provided, SDO outputs 0 for the remainder of the transaction frame and CLK_ERR is set.

SDO CRC Bits - CRCo[2:0] (DO[2:0]):

Read-mode transactions are protected by a 3-bit cyclic redundancy check (CRC) on the SDO data frame. CRC is provided by the slave on the last 3 bits on SDO.

CRC is calculated by applying the message DO[23:3] (i.e., ST + Data Requested) on polynomial $0x5 (x^3 + x^1 +$ x0) with a start value of binary 000.

The receiving device (master) calculates its own CRC using the same polynomial and starting value. The master only accepts/executes the command if its own CRC matches the last 3 bits on SDO.

Read-Mode Qualification Check (SPI_ERR):

To qualify for read-mode execution, the following conditions must be met:

- SPI transaction must be exactly 32 bits in length (no CLK_ERR recorded)
- SDI data frame CRC check must pass (no CRC_ERR recorded)
- DIN[12:0] must be all zeros (no R_ERR recorded)
- Individual call command CMD==01 received (no R_ERR recorder)

If the SPI read transaction is qualified, any clear-on-read internal register contents are updated, and the Internal Transaction Log updated with the content requested by the successful transaction.

Figure 9. Read-Mode Transaction

If the SPI read transaction is not qualified, clear-on-read internal register contents are not updated, the device's internal SPI_ERR indicator and appropriate SPI diagnostic bit are set, and the Internal Transaction Log updated to indicate the failed transaction. This SPI_ERR bit is returned in response to later read- and write-mode transactions, notifying the µC that the SPI may be compromised.

Note: The output data is always driven onto SDO, regardless of whether the read transaction is qualified or not.

General-Call Transactions:

A general-call transaction is an extension of the write transaction (see [Figure 10](#page-20-0)).

In large LED arrays where multiple MAX20092 devices are used, execute the same command across all devices to save time. For example, the master must have the ability set all LED1's PWM duty cycle to 50% for all 26 devices with a single 32-bit transaction.

Note: Only write transactions are legal for general-call transactions.

Write Bit - R/WB = 0 (DIN31):

Only write-mode transactions are legal. Write-mode transactions are identified by R/WB = 0 in the MSB position of a 32-bit data frame.

General-Call Command - CMD[1:0] = 10 (DIN[30:29]):

General-call transactions are identified by CMD[1:0] = 10 in the DIN[30:29] positions of the frame.

Device ID - ID[4:0] = 00000 (DIN[28:24])

Note: After the 8th bit has been received (8th rising SCLK edge), all slave devices pull down SDO for the remainder of the transaction.

Address - A[6:0] (DIN[22:16]):

General-call transactions allow new information to be written to internal configuration registers within the device.

The configuration register address to be written is indicated by A[6:0] within the data frame. In this format, up to 128 register addresses are supported (0\h thru 7F\h) for write-mode access.**Note:** DIN23 must always be 0.

Input Data - DIN[12:0] (DIN[15:3]):

The next 13 bits of data in the 32-bit data frame represent data that will be written to the requested register, or describe the internal operations to be executed.

SDI CRC Bit - CRCi[2:0] (DIN[2:0]):

General-call transactions are protected by a 3-bit cyclic redundancy check (CRC) on the SDI data frame. CRC is provided by the master on the last 3 bits on SDI.

It is calculated by applying the message DIN[31:3] (i.e., Address + Input Data) on polynomial 0x5 $(x^3 + x^1 + x^0)$ with a start value of binary 000

The receiving device (slave) calculates its own CRC using the same polynomial and starting value. The slave only accepts/executes the command if its own CRC matches the last 3 bits on SDI.

Output Data - DO[31:0]

During general-call transactions, the MAX20092 pulls down SDO following the falling edge of SCSB. The first 8 bits are always 0. After the 8th bit has been received, the SDO continues to be pulled down for the remainder of the transaction.

General-Call Qualification Check (SPI_ERR):

To qualify for general-call execution, the following conditions must be met:

- SPI transaction must be exactly 32 bits in length (no CLK_ERR recorded)
- SDI data frame CRC check must pass (no CRC_ERR recorded)
- A[6:0] must select a valid write-accessible register or command (no RW_ERR recorded)

Figure 10. General-Call Transaction

If the SPI transaction is qualified, the instruction is executed, any requested internal register contents are updated, and the Internal Transaction Log updated to indicate the successful transaction.

If the SPI write transaction is not qualified, the instruction is not executed, the device's internal SPI_ERR indicator and appropriate SPI diagnostic bit are set, and the Internal Transaction Log updated to indicate the failed transaction. The SPI_ERR bit is returned in response to later read- and write-mode transactions, notifying the µC that the SPI interface may be compromised.

Cluster-Call Transactions

A cluster-call transaction is an extension of the generalcall transaction (see [Figure 11\)](#page-21-0).

Multiple devices can be grouped into the same Cluster ID (configurable through a user-accessible register CID). This transaction allows the master to dim or brighten a cluster of LEDs with a single 32-bit transaction, but not affect LEDs assigned to a different Cluster ID.

Note: Only write transactions are legal for cluster-call transactions.

Cluster-Call Usage Example

In the cluster-call example (see [Figure 12](#page-22-0)), each string is vertically connected to one MAX20092 device. There are eight MAX20092 devices shown horizontally. Cluster 1 (CID=1) is assigned to the LEDs in the left headlight and cluster 2 (CID=2) is assigned to the LEDs in the right headlight. When an oncoming car is approaching on the right, the master sends a cluster transaction to CID=2 to reduce the duty cycle of all LEDs in the right cluster.

Write Bit - R/WB = 0 (DIN31):

Only write-mode transactions are legal. Write-mode transactions are identified by R/WB = 0 in the MSB position of a 32-bit data frame.

Cluster-Call Command - CMD[1:0] = 10 (DIN[30:29]):

Cluster-call transactions are identified by CMD[1:0] = 10 in the DIN[30:29] positions of the frame.

Cluster ID - CID[4:0] (DIN[28:24]):

The master provides a 5-bit Cluster ID following the cluster-call command. Slaves assigned to the Cluster ID continue to process the remainder of the command. **Note:** After the 8th bit has been received, all slave devices assigned to a predetermined cluster pull down SDO for the remainder of the transaction. Slave devices not assigned to cluster SDO are high impedance for the remainder of the transaction.

Address - A[6:0] (DIN[22:16]):

Cluster-call transactions allow new information to be written to internal configuration registers within the device. The configuration register address to write to is indicated by A[6:0] within the data frame. In this format, up to 128 register addresses are supported (0\h thru 7F\h) for writemode access. **Note:** DIN23 must always be 0.

Input Data - DIN[12:0] (DIN[15:3]):

The next 13 bits of data in the 32-bit data frame represent data that will be written to the requested register, or describes internal operations that must be executed.

SDI CRC Bit - CRCi[2:0] (DIN[2:0]):

Cluster-call transactions are protected by a 3-bit cyclic redundancy check (CRC) on the SDI data frame. CRC is provided by the master on the last 3 bits on SDI.

CRC is calculated by applying the DIN[31:3] message (i.e., Address + Input Data) on polynomial 0x5 $(x^{3}+ x^{1}+$ $(x⁰)$ with a start value of binary 000.

The receiving device (slave) calculates its own CRC using the same polynomial and starting value. The slave only accepts/executes the command if its own CRC matches the last 3 bits on SDI.

Figure 11. Cluster-Call Transaction

Figure 12. Cluster-Call Example

Output Data - DO[31:0]:

During cluster-call transactions, the device pulls down SDO following the falling edge of SCSB. The first 8 bits are always 0. After the 8th bit is received, all slave devices assigned to a predetermined cluster pull down SDO for the remainder of the transaction. Slave devices not assigned to a cluster do not connect SDO for the remainder of the transaction.

Cluster-Call Qualification Check (SPI_ERR):

To qualify for cluster call execution, the following conditions must be met:

- SPI transaction must be exactly 32 bits in length (no CLK_ERR recorded)
- SDI data frame CRC check must pass (no CRC_ERR recorded)
- A[6:0] must select a valid write-accessible register or command (no RW_ERR recorded)

If the SPI transaction is qualified, the instruction is executed, any requested internal register contents are updated, and the Internal Transaction Log updated to indicate the successful transaction.

If the SPI write transaction is not qualified, the instruction is not executed, the device's internal SPI_ERR indicator and appropriate SPI diagnostic bit are set, and the Internal Transaction Log updated to indicate the failed transaction. The SPI_ERR bit is returned in response to later read- and write-mode transactions, notifying the μ C that the SPI may be compromised.

SPI_ERR and SPI Diagnostic Bits

If the MAX20092 is provided with an unqualified transaction, the SPI_ERR bit is set to 1, allowing the master to observe the bit and made aware of the problem during every subsequent transaction. In addition to the SPI_ERR bit, detailed SPI diagnostic bits are available to help diagnose the interface:

- CLK_ERR: Issued for read- or write-mode transactions not exactly 32 bits in length or a SPI timeout occurs
- CRC_ERR: Issued for read- or write-mode transactions that fail CRC checks
- W_ERR: Issued for write-mode transactions to invalid addresses or CMD[1:0] equals 00\b or 11\b
- R_ERR: Issued for read-mode transactions where DIN[12:0] was not 0000\h or CMD[1:0] does not equal 01\b or read-mode transactions to invalid addresses

If multiple errors occur during a single transaction, only the first error is reported, in the order of precedence given above. This helps with identification of the root cause (e.g., a malformed transaction 33 SCLK cycles in length would fail the clock check, but may also fail CRC and address checks since the data is also likely misaligned as a result. In such cases, only the CLK_ERR SPI diagnostic bit is set).All SPI diagnostic bits are clear-on-read. Once asserted, they continue to read back as high until the content is cleared by reading back the SPI configuration register with a qualified read-mode transaction. The IC keeps a cumulative list of all SPI failure types observed during failed transactions.

Note: Transactions processed after any SPI diagnostic bit is set, and remain high, are qualified and executed/ accepted/logged normally, and their qualification can be determined by their inclusion in the Internal Transaction Log. Only transactions that individually fail qualification checks are shown as unqualified in the resulting Internal Transaction Log.

Internal Transaction Log

The Internal Transaction Log (LOG[23:0]) is updated on the SCSB rising edge after each SPI transaction. The contents of the log are determined by the read/write mode of the transaction and whether the transaction was qualified and executed. Details of the Internal Transaction Log content are explained in the following sections and summarized in [Table 4.](#page-23-1)

Table 4. Internal Transaction Log Contents

Read-Mode Transaction Log

If the completed transaction is qualified in read mode, the device will provide the current SPI_ERR status, the current device 7-bit status STR, 13-bit requested register data, and a 3-bit CRCo as LOG[23:0]. This allows the µC to frequently check the SPI integrity, response to the last transaction, and device status with minimal communication overhead in standard connections during every write-mode command issued. **Note:** The CRC and status information provided is fetched during the subsequent write-mode transaction (rather than being latched at the time of read-mode execution), providing the most current device information available.

$$
STR[0] = CP_RDY_N
$$

STR[1] = STAT_OPEN_LED[0] or STAT_OPEN_TRACE[0] or STAT_SHORT[0] or STAT_OPEN_LED[1] or STAT_OPEN_TRACE[1] or STAT_SHORT[1] or STAT_OPEN_LED[2] or STAT_OPEN_TRACE[2] or STAT_SHORT[2] STR[2] = STAT_OPEN_LED[3] or STAT_OPEN_TRACE[3] or STAT_SHORT[3] or STAT_OPEN_LED[4] or STAT_OPEN_TRACE[4] or STAT_SHORT[4] or STAT_OPEN_LED[5] or STAT_OPEN_TRACE[5] or STAT_SHORT[5] STR[3] = STAT_OPEN_LED[6] or STAT_OPEN_TRACE[6] or STAT_SHORT[6] or STAT_OPEN_LED[7] or STAT_OPEN_TRACE[7] or STAT_SHORT[7] or STAT_OPEN_LED[8] or STAT_OPEN_TRACE[8] or STAT_SHORT[8] STR[4] = STAT_OPEN_LED[9] or STAT_OPEN_TRACE[9] or STAT_SHORT[9] or STAT_OPEN_LED[10] or STAT_OPEN_TRACE[10] or STAT_SHORT[10] or STAT_OPEN_LED[11] or STAT_OPEN_TRACE[11] or STAT_SHORT[11] STR[5] = TH_SHDN or TH_WARN

 $STR[6] = 0$

CRCo is calculated by applying the message LOG[23:3] on polynomial 0x5 ($x^{3}+ x^{1}+ x^{0}$) with a start value of binary 000.

Write Mode + Initial Transaction Log

If there was no previous transaction due to a power-cycling event, the device returns the current SPI_ERR status $= 0$ as LOG[23], zeros in the address space, and a calculated 3-bit CRC bit as LOG[2:0]. The data bits return the device REV_ID[4:0], along with 11\h, allowing the µC to confirm integrity of the SDO data path and perform a CRC check on the initial SPI transaction following a POR event. CRCo is calculated by applying the message LOG[23:3] on polynomial 0x5 $(x³+x¹+x⁰)$ with a start value of binary 000.

Write Mode + Previous Transaction = Unqualified Transaction Log

If the previous transaction was unqualified and rejected, the device stores the current SPI_ERR status = 1 as LOG[23], a calculated 3-bit CRC as LOG[2:0]; the current/cumulative SPI diagnostic error and hardware reset status are returned as LOG[11:8] and all remaining LOG bits are set to zero. This allows the µC to be aware of the transaction failure during the following transaction. CRCo is calculated by applying the message LOG[23:3] on polynomial 0x5 ($x^{3}+ x^{1}+ x^{0}$) with a start value of binary 000.

Write Mode + Previous Transaction = Qualified Write Transaction Log

If the completed transaction is qualified/executed in write mode upon execution, the device will store the current SPI_ ERR status, the executed/previous A[6:0] and DIN[12:0] content as LOG[23:0]. This allows the µC to frequently check the SPI integrity and response to the last transaction with minimal communication overhead during every write-mode command issued. **Note:** This is the previously executed transaction data, not the internal content of any registers modified as a result of the transaction; use a read-mode transaction if an explicit verification of internal register content is desired. **Note:** Qualified general call and cluster-call commands are also considered qualified write transactions for the purposes of the transaction log.

CRCo is calculated by applying the message LOG[23:3] on polynomial 0x5 ($x^{3}+ x^{1}+ x^{0}$) with a start value of binary 000.

Write Mode + Previous Transaction = Qualified Read Transaction Log

If the completed transaction is qualified/executed in write mode, upon execution, the device will store the current SPI_ERR status, the executed/previous A[6:0], current device status (up to 13 bits) STR, and 3-bit CRCo content as LOG[23:0]. This allows the µC to frequently check SPI interface integrity and response to the last transaction with minimal communication overhead during every write mode command issued. Note this is the previously executed transaction data, not the internal content of any registers modified as a result of the transaction – use a read mode transaction if an explicit verification of internal register content is desired.

- STWR[0] = STAT_OPEN_LED[0] or STAT_OPEN_TRACE[0] or STAT_SHORT[0]
- STWR[1] = STAT_OPEN_LED[1] or STAT_OPEN_TRACE[1] or STAT_SHORT[1]
- STWR[2] = STAT_OPEN_LED[2] or STAT_OPEN_TRACE[2] or STAT_SHORT[2]
- STWR[3] = STAT_OPEN_LED[3] or STAT_OPEN_TRACE[3] or STAT_SHORT[3]
- STWR[4] = STAT_OPEN_LED[4] or STAT_OPEN_TRACE[4] or STAT_SHORT[4]
- STWR[5] = STAT_OPEN_LED[5] or STAT_OPEN_TRACE[5] or STAT_SHORT[5]
- STWR[6] = STAT_OPEN_LED[6] or STAT_OPEN_TRACE[6] or STAT_SHORT[6]
- STWR[7] = STAT_OPEN_LED[7] or STAT_OPEN_TRACE[7] or STAT_SHORT[7]
- STWR[8] = STAT_OPEN_LED[8] or STAT_OPEN_TRACE[8] or STAT_SHORT[8]
- STWR[9] = STAT_OPEN_LED[9] or STAT_OPEN_TRACE[9] or STAT_SHORT[9]
- STWR[10] = STAT_OPEN_LED[10] or STAT_OPEN_TRACE[10] or STAT_SHORT[12]
- STWR[11] = STAT_OPEN_LED[11] or STAT_OPEN_TRACE[11] or STAT_SHORT[11]
- STWR[12] = TH_SHDN or TH_WARN or CP_RDY_N

CRCo is calculated by applying the message LOG[23:3] on polynomial 0x5 $(x^{3}+ x^{1}+ x^{0})$ with a start value of binary 000.

Register Map

Register Map (continued)

Register Map (continued)

Register Details

NO_OP = [0x00](#page-26-1)

NO_OP is a read-only register that reads the content of RGRADE, revision ID, and test pattern.

SW_GO = [0x01](#page-26-2)

SW_GO is a read/write register that enables the PWM signals.

CNFG_SPI = [0x02](#page-26-3)

CNFG_SPI is a read/write access register that controls how the SPI is configured: the cluster ID assignment and whether the internal safety terminations are engaged.

In read mode, four interface status bits are added. The SPI error indicator bits (_ERR) show what type(s) of SPI transaction errors have occurred for the MAX20092 since CNFG_SPI was last read. Once read back, their status is returned to zero (clear-on-read). SPI_ERR is the combination of the three error indicator bits:

SPI_ERR = (CLK_ERR or PAR_ERR or RW_ERROR)

CNFG_GEN = [0x03](#page-26-4)

CNFG_GEN is a read/write access register that controls the dimming clock divider ratio, the slew rate of the LED switches, the threshold used for the short-LED fault-detection function, and the functionality of the CLK pin.

CNFG_MSK = [0x04](#page-26-5)

CNFG_MSK is a read/write access register that controls the masking of fault conditions from the FAULTB pin.

STAT_GEN = [0x05](#page-26-6)

STAT_GEN is a read-only access register that provides general operations and warnings. FAULTB is asserted whenever any of these bits is high, unless the corresponding MASK bit is set.

STAT_OPEN_LED = [0x06](#page-26-7)

STAT_OPEN is a read-only access register that provides open-detect information on the 12 LED output drivers.

STAT_OPEN_TRACE = [0x07](#page-26-8)

STAT_OPEN_TRACE is a read-only register that provides open-trace fault information on the 12 LED output drivers.

OPEN_OVRD = [0x08](#page-26-9)

OPEN_OVRD is a read/write register that overrides the LED switching control signals. When this feature is disabled, the LED switch operates normally. When this feature is enabled, the LED switch is always forced to a closed position (i.e., the LED duty cycle is zero, regardless of the DUTY or TDIM settings).The intent is to allow the μP to manually force the switch to stay closed after it has determined the particular LED is permanently opened. This further suppresses FAULTB signals from the switch(es) since LED faults are only detected when the switch opens.

STAT_SHORT_LED = [0x09](#page-26-10)

STAT_SHORT_LED is a read-only access register that provides short-detect information on the 12 LED output drivers.

CNFG_GROUPA = [0x0A](#page-26-11)

CNFG_GRPA is a read/write register that allows the user to assign particular LED drivers to a this group. LED drivers assigned to this group respond to qualified transactions on the following registers:

- PSFT_GRP (if PSFT_GROUP==0001)
- TDIM_GROUP (if TDIM_GROUP=0001)
- PWM GRPA DUTY

CNFG_GROUPB = [0x0B](#page-26-12)

CNFG_GRPB is a read/write register that allows the user to assign particular LED drivers to a this group. LED drivers assigned to this group respond to qualified transactions on the following registers:

- PSFT_GRP (if PSFT_GROUP==00010)
- TDIM_GROUP (if TDIM_GROUP=0010)
- PWM_GRPB_DUTY

CNFG_GROUPC = [0x0C](#page-26-13)

CNFG_GRPC is a read/write register that allows the user to assign particular LED drivers to a this group. LED drivers assigned to this group respond to qualified transactions on the following registers:

- PSFT_GRP (if PSFT_GROUP==0100)
- TDIM_GROUP (if TDIM_GROUP=0100)
- PWM_GRPc_DUTY

CNFG_GROUPD = [0x0D](#page-26-14)

CNFG_GRPD is a read/write register that allows the user to assign particular LED drivers to a this group. LED drivers assigned to this group respond to qualified transactions on the following registers:

- PSFT_GRP (if PSFT_GROUP==1000)
- TDIM_GROUP (if TDIM_GROUP=1000)
- PWM_GRPD_DUTY

GROUPD

CNFG_MSK_LED = [0x0E](#page-26-15)

CNFG_MSK_LED prevents LED faults from asserting the FAULTB pin. This allows the μP to instruct the part to ignore faults from a particular LED when that LED is deliberately not populated in the application.

PSFT_GRP = [0x10](#page-27-0)

PSFT_GRP is a read/write register that allows the user to assign the same phase shift to one or more LED drivers.

The contents of PSFT are written to the desired group specified by PSFT GROUP.Example:If PSFT GROUP == Group A, PSFT == 0001, and LED11, LED9, and LED6 are assigned to Group A (through CNFG_GRPA), then PSFT_11, PSFT_9, and PSFT_6 will contain 0001 after the transaction is executed.

from those LEDs asserting FAULTB.

PSFT_2_1_0 = [0x11](#page-27-1)

PSFT_2_1_0 is a read/write register that controls the phase shift for LED drivers 0, 1, and 2.

PSFT_5_4_3 = [0x12](#page-27-2)

PSFT_5_4_3 is a read/write register that controls the phase shift for LED drivers 3, 4, and 5.

PSFT_8_7_6 = [0x13](#page-27-3)

PSFT_8_7_6 is a read/write register that controls the phase shift for LED drivers 6, 7, and 8.

PSFT_11_10_9 = [0x14](#page-27-4)

PSFT_11_10_9 is a read/write register that controls the phase shift for LED drivers 9, 10, and 11.

TDIM_GRP = [0x18](#page-27-5)

TDIM_GRP is a read/write register that allows the user to assign the same dimming period to one or more LED drivers. The contents of TDIM are written to the desired group specified by TDIM_GROUP.Example:If TDIM_GROUP == Group A, PSFT == 001, and LED12, LED9, and LED6 are assigned to Group A (through CNFG_GRPA), then TDIM_12, TDIM_9, and TDIM_6 will contain 001 after the transaction is executed.

TDIM_2_1_0 = [0x19](#page-27-6)

TDIM_2_1_0 is a read/write register that controls the dimming period for LED drivers 2, 1, and 0.

TDIM_5_4_3 = [0x1A](#page-27-7)

TDIM_5_4_3 is a read/write register that controls the dimming period for LED drivers 5, 4, and 3.

TDIM_8_7_6 = [0x1B](#page-27-8)

TDIM_8_7_6 is a read/write register that controls the dimming period for LED drivers 8, 7, and 6.

TDIM_11_10_9 = [0x1C](#page-27-9)

TDIM_11_10_9 is a read/write register that controls the dimming period for LED drivers 11, 10, and 9.

PWM_GRPA_DUTY = [0x20](#page-27-10)

PWM_GRPA_DUTY is a read/write register that allows the user to assign the same duty cycle and enable/disable PWM dimming to one or more LED drivers.

The contents of DUTY_A are written to LEDs assigned to Group A.

Example: If DUTY_A == 0x0AA and LED11, LED8, and LED5 are assigned to Group A (through CNFG_GRPA), then DUTY_11, DUTY_8, and DUTY_5 will contain 0x0AA after the transaction is executed.

PWM_GRPB_DUTY = [0x21](#page-27-11)

PWM_GRPB_DUTY is a read/write register that allows the user to assign the same duty cycle and enable/disable PWM dimming to one or more LED drivers.

The contents of DUTY_B are written to LEDs assigned to Group B.

Example: If DUTY_B == 0x0AA and LED11, LED9, and LED6 are assigned to Group B (through CNFG_GRPB), then DUTY_11, DUTY_9, and DUTY_6 will contain 0x0AA after the transaction is executed.

PWM_GRPC_DUTY = [0x22](#page-27-12)

PWM_GRPC_DUTY is a read/write register that allows the user to assign the same duty cycle and enable/disable PWM dimming to one or more LED drivers.

The contents of DUTY_C are written to LEDs assigned to Group B.Example:

If DUTY_C == 0x0AA and LED11, LED9, and LED6 are assigned to Group C (through CNFG_GRPC), then DUTY_11, DUTY_9, and DUTY_6 will contain 0x0AA after the transaction is executed.

PWM_GRPD_DUTY = [0x23](#page-27-13)

PWM_GRPD_DUTY is a read/write register that allows the user to assign the same duty cycle and enable/disable PWM dimming to one or more LED drivers.

The contents of DUTY_D are written to LEDs assigned to Group D.Example: If DUTY_D == 0x0AA and LED11, LED9, and LED6 are assigned to Group B (through CNFG_GRPD), then DUTY_11, DUTY_9, and DUTY_6 will contain 0x0AA after the transaction is executed.

PWM0 = [0x24](#page-27-14)

PWM0 is a read/write register that configures the LED0 duty cycle and enables/disables PWM dimming.

PWM1 = [0x25](#page-27-15)

PWM1 is a read/write register that configures the LED1 duty cycle and enables/disables PWM dimming.

PWM2 = [0x26](#page-27-16)

PWM2 is a read/write register that configures the LED2 duty cycle and enables/disables PWM dimming.

PWM3 = [0x27](#page-27-17)

PWM3 is a read/write register that configures the LED3 duty cycle and enables/disables PWM dimming.

PWM4 = [0x28](#page-27-18)

PWM4 is a read/write register that configures the LED4 duty cycle and enables/disables PWM dimming.

PWM5 = [0x29](#page-28-1)

PWM5 is a read/write register that configures the LED5 duty cycle and enables/disables PWM dimming.

PWM6 = [0x2A](#page-28-2)

PWM6 is a read/write register that configures the LED6 duty cycle and enables/disables PWM dimming.

PWM7 = [0x2B](#page-28-3)

PWM7 is a read/write register that configures the LED7 duty cycle and enables/disables PWM dimming.

PWM8 = [0x2C](#page-28-4)

PWM8 is a read/write register that configures the LED8 duty cycle and enables/disables PWM dimming.

PWM9 = [0x2D](#page-28-5)

PWM9 is a read/write register that configures the LED9 duty cycle and enables/disables PWM dimming.

PWM10 = [0x2E](#page-28-6)

PWM10 is a read/write register that configures the LED10 duty cycle and enables/disables PWM dimming.

PWM11 = [0x2F](#page-28-7)

PWM11 is a read/write register that configures the LED11 duty cycle and enables/disables PWM dimming.

Typical Application Circuits

Ordering Information

/V Denotes an automotive-qualified part.

+*Denotes a lead(Pb)-free/RoHS-compliant package.*

SW = Side-wettable TQFN package.

**EP = Exposed pad.*

T = Tape-and-reel package.